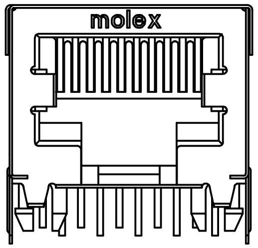
NOTES:
1) MATERIAL:
HOUSING: NYLON(PA), GLASS FILLED, UL94V-0, COLOR: BLACK
INSULATOR: NYLON(PA), GLASS FILLED, UL94V-0, COLOR: BLACK
TERMINALS: PHOSPHOR BRONZE, .012/(0.30) THICK
SHIELD: BRASS, .007/(0.18) THICK
2) FINISH:
TERMINALS:
A = SELECT GOLD IN CONTACT AREA: 50 MICROINCHES / 1.27 MICROMETERS MIN.,
∗SELECT TIN IN PC TAIL AREA: 100 MICROINCHES / 2.54 MICROMETERS MIN.,
WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES / 1.27 MICROMETERS MIN.
B = SELECT GOLD IN CONTACT AREA: 30 MICROINCHES / 0.76 MICROMETERS MIN.,
∗SELECT TIN IN PC TAIL AREA: 100 MICROINCHES / 2.54 MICROMETERS MIN.,
WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES / 1.27 MICROMETERS MIN.
SHIELD:
∗100 MICROINCHES / 2.54 MICROMETERS NICKEL OVER 50 MICROINCHES /
1.27 MICROMETERS COPPER UNDERPLATE, PCB GROUND TABS DIPPED IN TIN
∗THE PRIMARY SHIPPING CARTON WILL BE LABELED "COMPLIANT TO RoHS DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE 2000/53/EC". CARTONS WITHOUT THIS LABEL MAY CONTAIN PRODUCT WITH TIN-LEAD IN THE PC TAILS AND/OR SHIELD.
3) PRODUCT SPECIFICATION AND PROCESSING PARAMETERS: PS-43249.
4) PACKAGING SPECIFICATION:
UNSHIELDED CONNECTOR ASSEMBLIES PACKAGED IN THERMOFORMED TRAYS PER MOLEX PACKAGING SPECIFICATION PK-43249-004.
UNSHIELDED CONNECTOR ASSEMBLIES PACKAGED IN TUBES PER MOLEX PACKAGING SPECIFICATION PK-43249-005.
SHIELDED CONNECTOR ASSEMBLIES PACKAGED IN THERMOFORMED TRAYS PER MOLEX PACKAGING SPECIFICATION PK-44050-004.
5) MATES WITH: MODULAR PLUGS THAT CONFORM TO FCC REGULATION PART 68.5.
6) SEE SHEET 3 FOR SHIELDED JACK ASSEMBLY.
7) SEE SHEETS 5 & 6 FOR P.C. BOARD LAYOUTS.
8) ALL UNTOLERANCED DIMENSIONS ARE SHOWN FOR REFERENCE ONLY.
9) THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC SPECIFICATION PS-45499-002.
10) THIS PART CONFORMS TO FCC REGULATION 68.5 AND TIA 1096 FOR MODULAR JACKS.

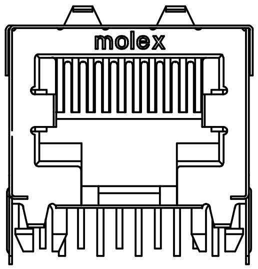
DRAWING LEGEND

SHEET 1-	NOTES; GROUND TAB OPTIONS
SHEET 2-	UNSHIELDED MODULAR JACK
SHEET 3-	SHIELDED MODULAR JACK WITH OPTIONAL SIDE/TOP GROUND TABS & BOTTOM GROUND TAB WITH OPTIONAL POSITION.
SHEET 4-	PART NUMBER CHARTS
SHEET 5-	FOOTPRINT LAYOUT FOR 8 POSITION HOUSING
SHEET 6-	FOOTPRINT LAYOUT FOR 6 POSITION HOUSING

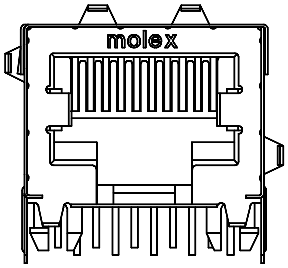
SIDE/TOP GROUND TAB OPTIONS FOR SHIELDS



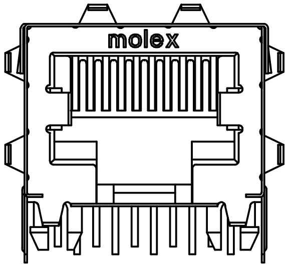
OPTION "A"
NO TOP OR SIDE TABS



OPTION "B"
TOP TABS

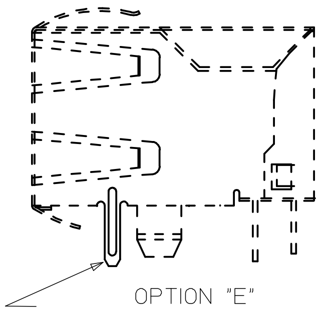


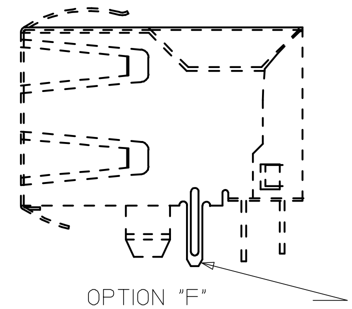
OPTION "C"
TOP AND STAGGERED SIDE TABS



OPTION "D"
TOP AND SIDE TABS

BOTTOM PCB GROUND TAB OPTIONS FOR SHIELDS


OPTION "E"
OPTIONAL FRONT POSITION


OPTION "F"
OPTIONAL REAR POSITION

NOTE: EITHER PCB GROUND TAB OPTION IS AVAILABLE ON ALL SIDE/TOP TAB CONFIGURATIONS

ADDED NOTE 10
EC NO: UCP2009-0740
DRWN:JKLOSTEMEIER 2008/09/29
CH'KD:JBELL 2008/10/03
APPR:FSMITH 2008/10/03
DESCRIPTION
K1
REV

QUALITY SYMBOLS
▼=0
▽C=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± .010
2 PLACES	± 0.25	± ---
1 PLACE	± ---	± ---
ANGULAR ±1/2°		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

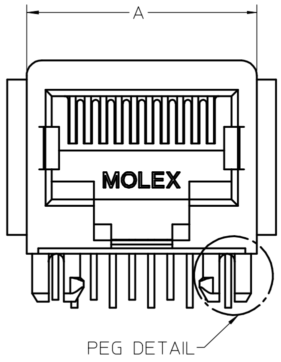
DIMENSION STYLE: IN/MM
SCALE: 4:1
DESIGN UNITS: INCH
THIRD ANGLE PROJECTION

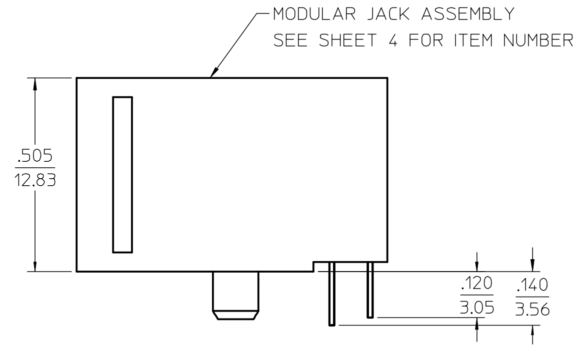
DRAWN BY: JTR	DATE: 1993/06/23
CHECKED BY: JTR	DATE: 1993/06/23
APPROVED BY: RAS	DATE: 1993/06/23

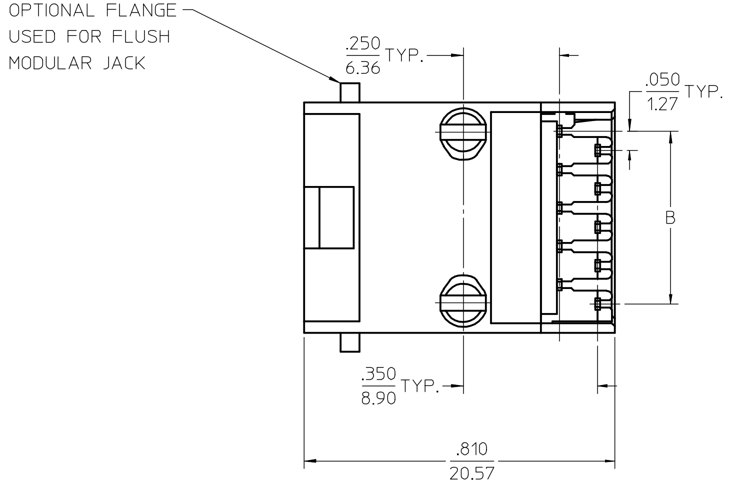
TITLE: LOW PROFILE RIGHT ANGLE MODULAR JACK ASSEMBLY
molex MOLEX INCORPORATED
MATERIAL NO.: SEE SHEET 4
DOCUMENT NO.: SDA-43249
SHEET NO.: 1 OF 6
SIZE: C

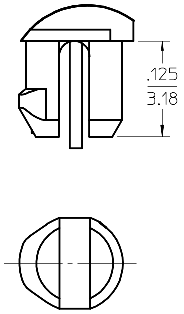
UNSHIELDED MODULAR JACK

8 POSITION LOADED 10 SIZE SHOWN

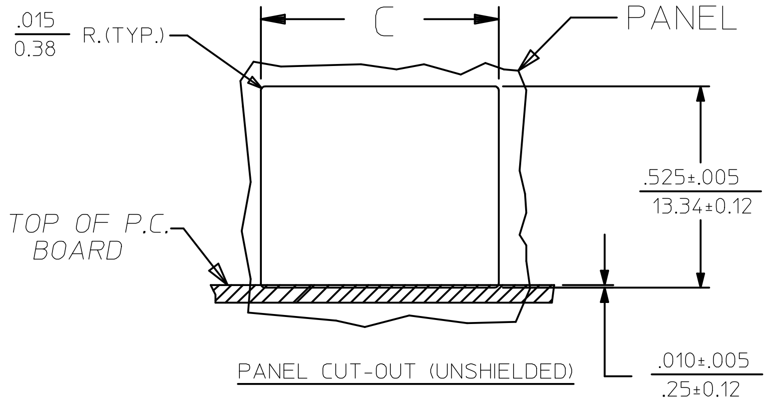








PEG DETAIL
SCALE 8:1



PANEL CUT-OUT (UNSHIELDED)

HOUSING SIZE	CIRCUIT SIZE	DIM. A	DIM. B	DIM. C
8	10	.600±.005 (15.24±0.13)	.450±.005 (11.43±0.13)	.620±.005 (15.75±0.13)
8	8	.600±.005 (15.24±0.13)	.350±.005 (8.89±0.13)	.620±.005 (15.75±0.13)
8	4	.600±.005 (15.24±0.13)	.150±.005 (3.81±0.13)	.620±.005 (15.75±0.13)
8	6	.600±.005 (15.24±0.13)	.250±.005 (6.35±0.13)	.620±.005 (15.75±0.13)
6	6	.520±.005 (13.21±0.13)	.250±.005 (6.35±0.13)	.540±.005 (13.72±0.13)
6	4	.520±.005 (13.21±0.13)	.150±.005 (3.81±0.13)	.540±.005 (13.72±0.13)
6	2	.520±.005 (13.21±0.13)	.050±.005 (1.27±0.13)	.540±.005 (13.72±0.13)

SEE SHEET 1
EC NO: UCP2009-0740
DRWN: JKLOSTEMEIER 2008/09/29
CH'KD: JBELL 2008/10/03
APPR: FSMITH 2008/10/03
DESCRIPTION
K1
REV

QUALITY SYMBOLS
▼=0
∇=0

GENERAL TOLERANCES
(UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	±.010
2 PLACES	± 0.25	± ---
1 PLACE	± ---	± ---

ANGULAR ±1/2°

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE	SCALE	DESIGN UNITS
IN/MM	4:1	INCH

THIRD ANGLE PROJECTION

	NAME	DATE
DRAWN BY	JTR	1993/06/23
CHECKED BY	JTR	1993/06/23
APPROVED BY	RAS	1993/06/23

TITLE
LOW PROFILE RIGHT ANGLE
MODULAR JACK ASSEMBLY

molex MOLEX INCORPORATED

MATERIAL NO.
SEE SHEET 4

DOCUMENT NO.
SDA-43249

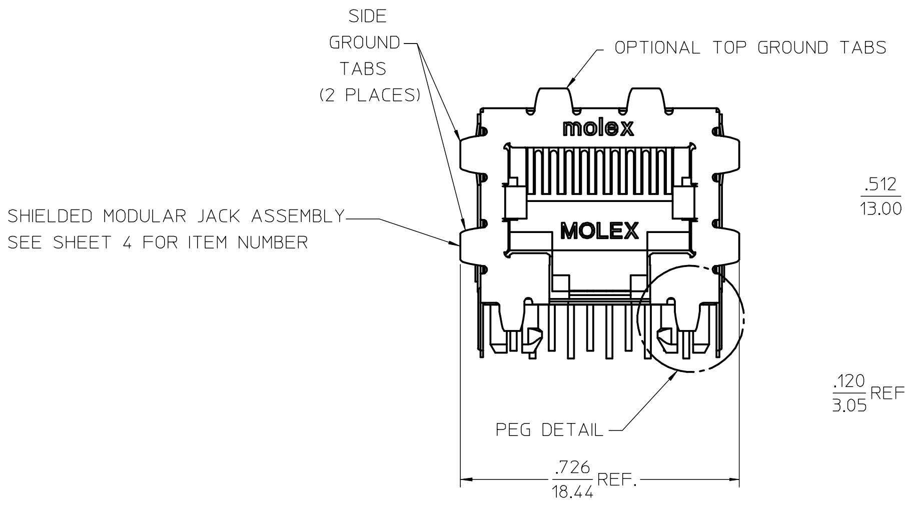
SHEET NO.
2 OF 6

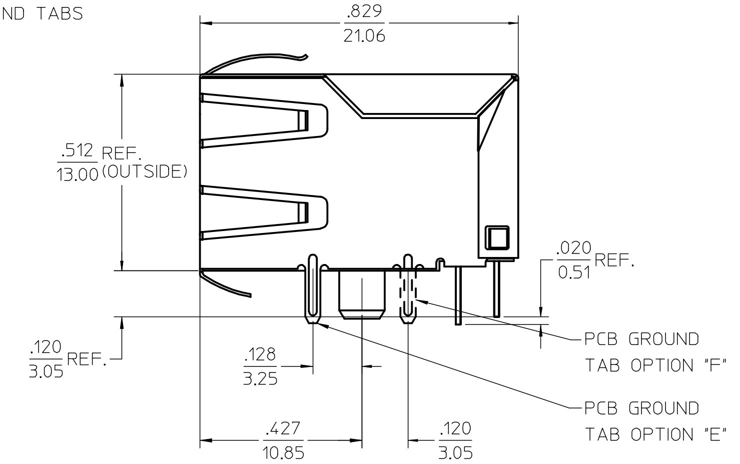
SIZE
C

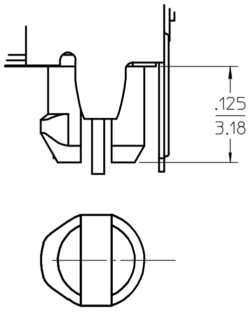
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

MODULAR JACK W/ .007" THICK SHIELD AND OPTIONAL GROUND TABS

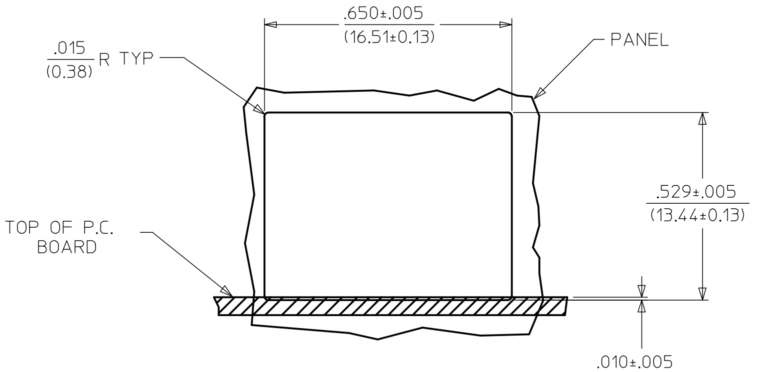
8 LOADED 10 VERSION SHOWN WITH GROUND TAB OPTIONS "D" AND "E"



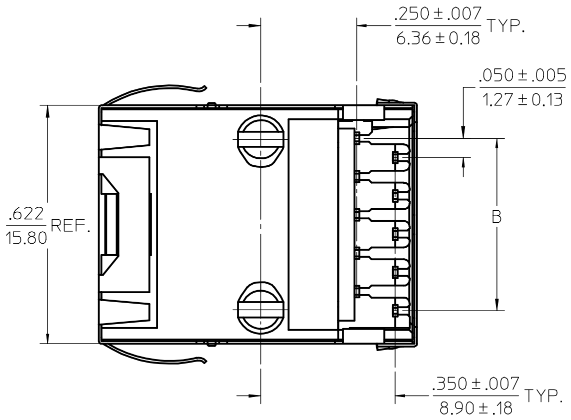




PEG DETAIL
SCALE 8:1



PANEL CUT-OUT (SHIELDED)



DESCRIPTION OF GROUND TAB OPTIONS:
(SEE SHEET 4 FOR AVAILABLE COMBINATIONS OF OPTIONS)

GROUND TAB OPTION	DESCRIPTION
A	NO GROUND TABS
B	TOP TABS ONLY
C	STAGGERED SIDE TABS
D	TOP AND SIDE TABS
E	PCB GROUND TAB IN FRONT POSITION
F	PCB GROUND TAB IN REAR POSITION

HOUSING SIZE	CIRCUIT SIZE	B
8	10	.450±.005 11.43±0.13
8	8	.350±.005 8.89±0.13

SEE SHEET 1
EC NO: UCP2009-0740
DRWN: JKLOSTEMEIER 2008/09/29
CHK'D: JBELL 2008/10/03
APPR: FSMITH 2008/10/03
DESCRIPTION
K1
REV

QUALITY SYMBOLS
▼=0
∇=0

GENERAL TOLERANCES
(UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± .010
2 PLACES	± 0.25	± ---
1 PLACE	± ---	± ---
ANGULAR ±1/2°		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: IN/MM	SCALE: 4:1	DESIGN UNITS: INCH
DRAWN BY: JTR	DATE: 1993/06/23	
CHECKED BY: JTR	DATE: 1993/06/23	
APPROVED BY: RAS	DATE: 1993/06/23	
MATERIAL NO.: SEE SHEET 4	DOCUMENT NO.: SDA-43249	SHEET NO.: 3 OF 6

THIRD ANGLE PROJECTION

TITLE
LOW PROFILE RIGHT ANGLE
MODULAR JACK ASSEMBLY

molex MOLEX INCORPORATED

SIZE C

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

FLUSH MOUNT (UNSHIELDED)

ASSEMBLY ITEM NUMBER	CONNECTOR SIZE	NUMBER OF CIRCUITS	TERMINAL PLATING OPTION
43249-8001	8	10	A
43249-8004	8	8	A
43249-8010	8	6	A
43249-6001	6	6	A
43249-6004	6	4	A
43249-6007	6	2	A

FLANGELESS (UNSHIELDED)

ASSEMBLY ITEM NUMBER	CONNECTOR SIZE	NUMBER OF CIRCUITS	TERMINAL PLATING OPTION
43249-8101	8	10	A
43249-8102	8	10	B
43249-8104	8	8	A
43249-8105	8	8	B
43249-8116	8	6	A
43249-8119	8	4	A
43249-6101	6	6	A
43249-6104	6	4	A
43249-6107	6	2	A

FLANGELESS (UNSHIELDED)

(SHIPPED IN TUBES)

43249-6501	6	6	A
43249-6504	6	4	A

SHIELDED, .007" THICK

ASSEMBLY ITEM NUMBER	CONN. SIZE	NUMBER OF CIRCUITS	TERMINAL PLATING OPTION	SIDE/TOP PANEL GROUND TAB OPTION	PCB GROUND TAB OPTION	PACKAGING OPTION
43249-8900	8	10	A	A	E	TRAY
43249-8901	8	10	A	B	E	TRAY
43249-8902	8	10	A	C	E	TRAY
43249-8903	8	10	A	D	E	TRAY
43249-8908	8	10	A	A	F	TRAY
43249-8909	8	10	A	B	F	TRAY
43249-8910	8	10	A	C	F	TRAY
43249-8911	8	10	A	D	F	TRAY
43249-8916	8	8	A	A	E	TRAY
43249-8917	8	8	A	B	E	TRAY
43249-8918	8	8	A	C	E	TRAY
43249-8919	8	8	A	D	E	TRAY
43249-8920	8	8	B	A	E	TRAY
43249-8924	8	8	A	A	F	TRAY
43249-8925	8	8	A	B	F	TRAY
43249-8926	8	8	A	C	F	TRAY
43249-8927	8	8	A	D	F	TRAY

SEE SHEET 1
EC NO: UCP2009-0740
DRWN:JKLOSTEMEIER 2008/09/29
CH'KD:JBELL 2008/10/03
APPR:FSMITH 2008/10/03
DESCRIPTION
K1
REV

QUALITY SYMBOLS
▼=0
▽=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± .010
2 PLACES	± 0.25	± ---
1 PLACE	± ---	± ---

ANGULAR ±1/2°

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

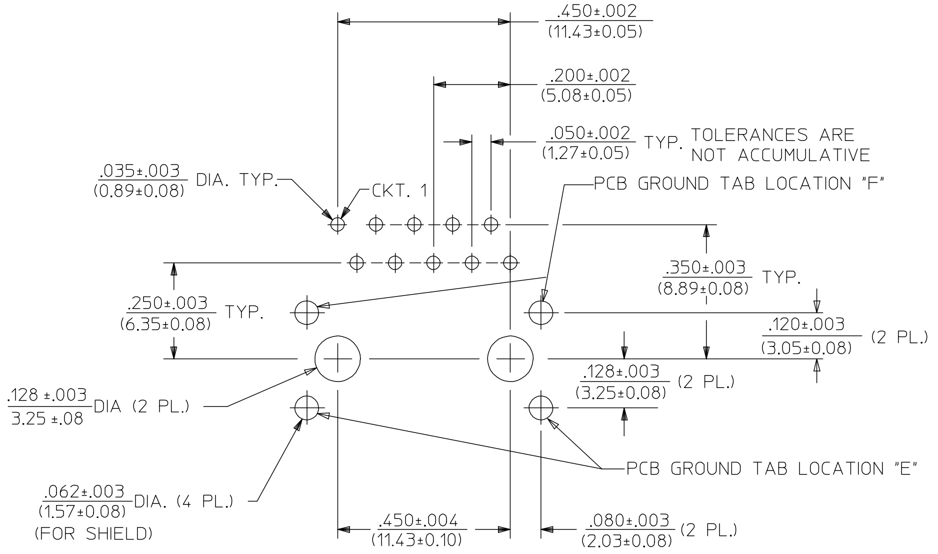
DIMENSION STYLE: IN/MM	SCALE: 4:1	DESIGN UNITS: INCH
DRAWN BY: JTR	DATE: 1993/06/23	
CHECKED BY: JTR	DATE: 1993/06/23	
APPROVED BY: RAS	DATE: 1993/06/23	
MATERIAL NO.: SEE CHART	DOCUMENT NO.: SDA-43249	SHEET NO.: 4 OF 6

THIRD ANGLE PROJECTION

TITLE
LOW PROFILE RIGHT ANGLE MODULAR JACK ASSEMBLY

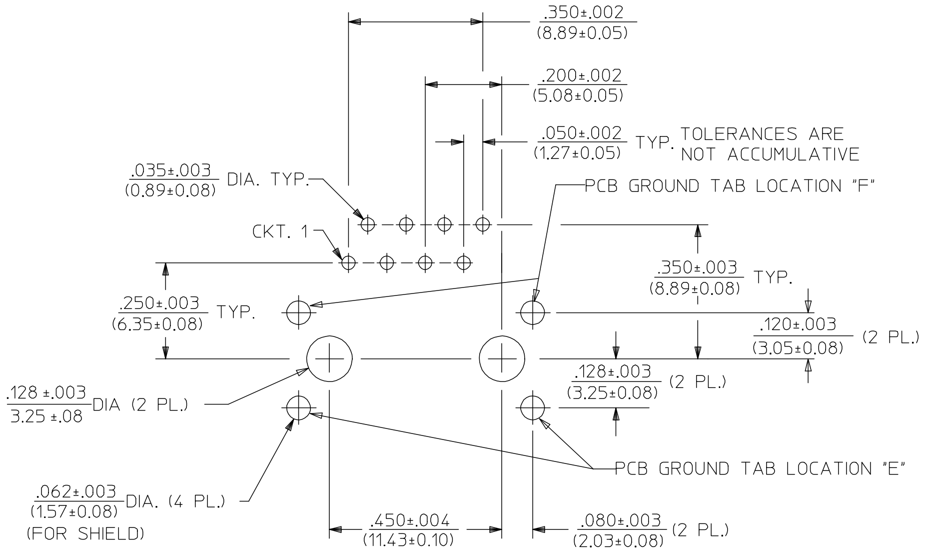
molex MOLEX INCORPORATED

SIZE C



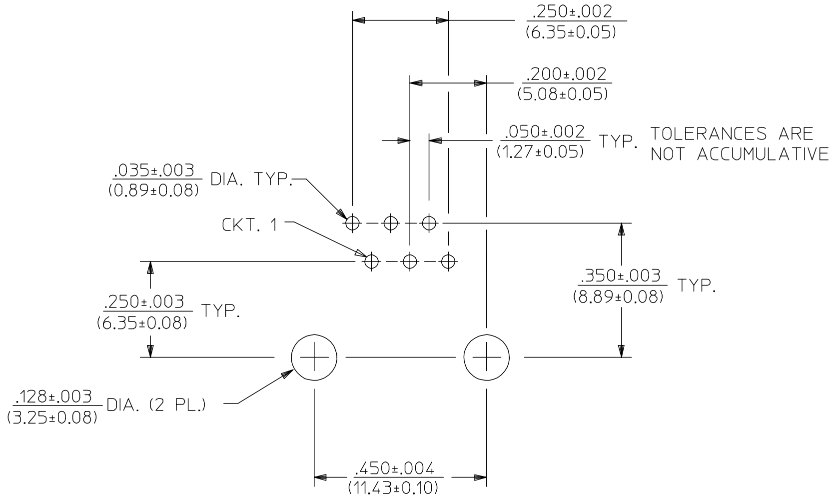
PC BOARD LAYOUT FOR SIZE 8, 10 CIRCUIT

(COMPONENT SIDE OF BOARD)



PC BOARD LAYOUT FOR SIZE 8, 8 CIRCUIT

(COMPONENT SIDE OF BOARD)



PC BOARD LAYOUT FOR SIZE 8, 6 CIRCUIT

(COMPONENT SIDE OF BOARD)

NOTES:
1. RECOMMENDED PCB THICKNESS: .062±.005/(1.57±0.13)

SEE SHEET 1
EC NO: UCP2009-0740
DRWN:JKLOSTEMEIER 2008/09/29
CH'KD:JBELL 2008/10/03
APPR:FSMITH 2008/10/03
DESCRIPTION
K1
REV

QUALITY SYMBOLS
▼=0
◁C▷=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	±.010
2 PLACES	± 0.25	± ---
1 PLACE	± ---	± ---
ANGULAR ±1/2°		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

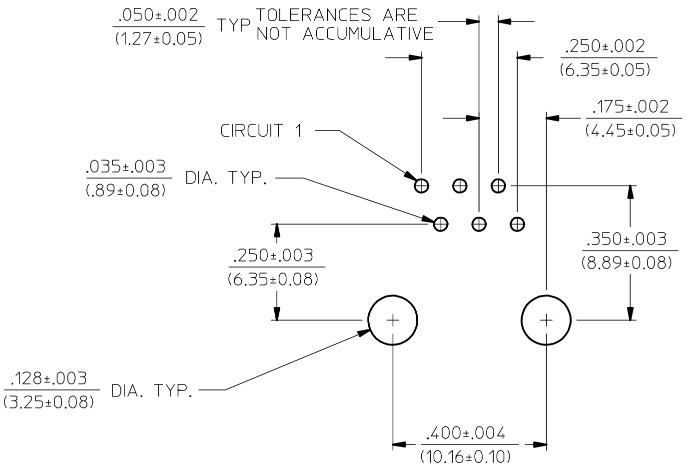
DIMENSION STYLE: IN/MM
SCALE: 4:1
DESIGN UNITS: INCH
THIRD ANGLE PROJECTION

DRAWN BY: JTR DATE: 1993/06/23
CHECKED BY: JTR DATE: 1993/06/23
APPROVED BY: RAS DATE: 1993/06/23

TITLE: LOW PROFILE RIGHT ANGLE MODULAR JACK ASSEMBLY

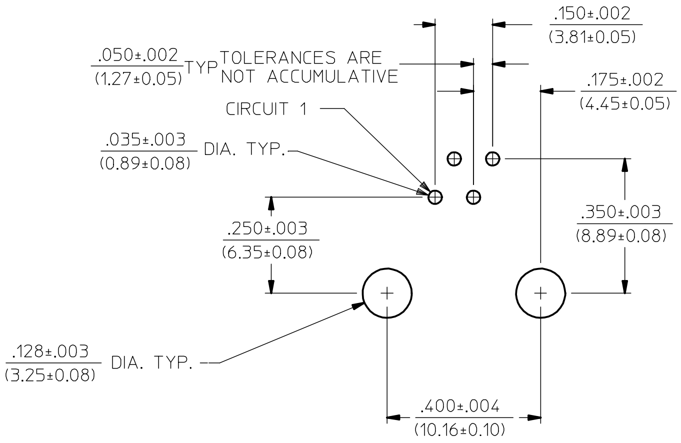
molex MOLEX INCORPORATED

MATERIAL NO.: SEE SHEET 4
DOCUMENT NO.: SDA-43249
SHEET NO.: 5 OF 6
SIZE: C



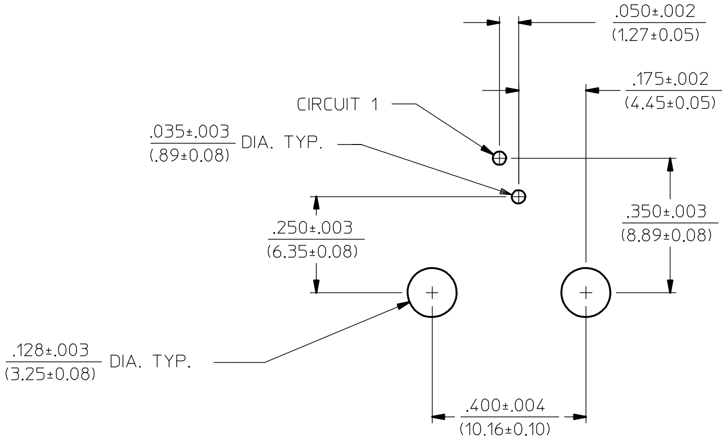
PC BOARD LAYOUT FOR SIZE 6, 6 CIRCUIT

(COMPONENT SIDE OF BOARD)



PC BOARD LAYOUT FOR SIZE 6, 4 CIRCUIT

(COMPONENT SIDE OF BOARD)



PC BOARD LAYOUT FOR SIZE 6, 2 CIRCUIT

(COMPONENT SIDE OF BOARD)

NOTES:
1. RECOMMENDED PCB THICKNESS: .062±.005/(1.57±0.13)

SEE SHEET 1
EC NO: UCP2009-0740
DRWN: JKLOSTEMEIER 2008/09/29
CH'KD: JBELL 2008/10/03
APPR: FSMITH 2008/10/03
DESCRIPTION
K1
REV

QUALITY SYMBOLS
▼=0
▽=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± .010
2 PLACES	± 0.25	± ---
1 PLACE	± ---	± ---
ANGULAR ±1/2°		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE IN/MM	SCALE 4:1	DESIGN UNITS INCH
DRAWN BY JTR	DATE 1993/06/23	THIRD ANGLE PROJECTION
CHECKED BY JTR	DATE 1993/06/23	
APPROVED BY RAS	DATE 1993/06/23	
MATERIAL NO. SEE SHEET 4	DOCUMENT NO. SDA-43249	SHEET NO. 6 OF 6
SIZE C		

TITLE
LOW PROFILE RIGHT ANGLE MODULAR JACK ASSEMBLY

MOLEX INCORPORATED

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

LifeElectronics
Живое партнерство

ООО "ЛайфЭлектроникс" **"LifeElectronics" LLC**

ИНН 7805602321 КПП 780501001 Р/С 40702810122510004610 ФАКБ "АБСОЛЮТ БАНК" (ЗАО) в г.Санкт-Петербурге К/С 30101810900000000703 БИК 044030703

Компания «Life Electronics» занимается поставками электронных компонентов импортного и отечественного производства от производителей и со складов крупных дистрибьюторов Европы, Америки и Азии.

С конца 2013 года компания активно расширяет линейку поставок компонентов по направлению коаксиальный кабель, кварцевые генераторы и конденсаторы (керамические, пленочные, электролитические), за счёт заключения дистрибьюторских договоров

Мы предлагаем:

- *Конкурентоспособные цены и скидки постоянным клиентам.*
- *Специальные условия для постоянных клиентов.*
- *Подбор аналогов.*
- *Поставку компонентов в любых объемах, удовлетворяющих вашим потребностям.*

- *Приемлемые сроки поставки, возможна ускоренная поставка.*
- *Доставку товара в любую точку России и стран СНГ.*
- *Комплексную поставку.*
- *Работу по проектам и поставку образцов.*
- *Формирование склада под заказчика.*

- *Сертификаты соответствия на поставляемую продукцию (по желанию клиента).*
- *Тестирование поставляемой продукции.*
- *Поставку компонентов, требующих военную и космическую приемку.*
- *Входной контроль качества.*
- *Наличие сертификата ISO.*

В составе нашей компании организован Конструкторский отдел, призванный помогать разработчикам, и инженерам.

Конструкторский отдел помогает осуществить:

- *Регистрацию проекта у производителя компонентов.*
- *Техническую поддержку проекта.*
- *Защиту от снятия компонента с производства.*
- *Оценку стоимости проекта по компонентам.*
- *Изготовление тестовой платы монтаж и пусконаладочные работы.*

BURR-BROWN BB, EXAR, Lattice, CATALYST, MITSUBISHI, TUNDRA, CIRRUS LOGIC, intersil, Panasonic, LINEAR TECHNOLOGY, ATMEL, AMD, FAIRCHILD SEMICONDUCTOR
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